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Jul 13 '05 17:22 P.08/08

Customer No.: 31561
Application No.: 10/707,015
Docket NO.: 10542-US-PA

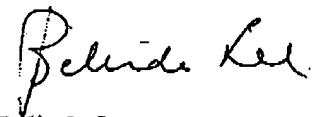
REMARKS

In response to the Office Action, mailed June 15, 2005, a complete listing of all of the claims is presented herewith. Applicant would like to elect Group I, claims 1-10, drawn to a process for fabricating a substrate, classified in class 29, subclass 830+. Please cancel Group II, claims 11-14, drawn to a substrate, classified in class 174, subclass 255, without waiver, prejudice or disclaimer.

If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date: *July 13, 2005*



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